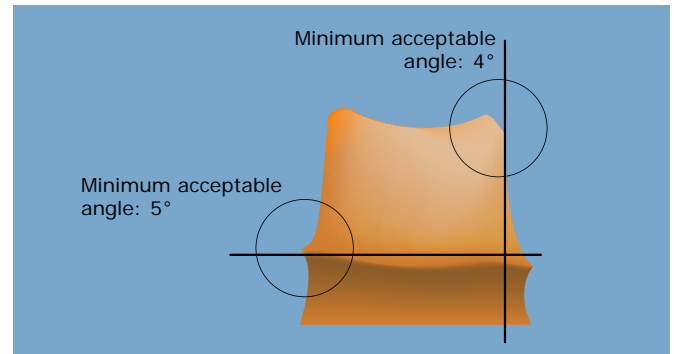


LABORATORY PREPARATION FOR DIGITAL PROCESSING

- A light colored type IV or V die stone (white, beige, buff or green) without plastic additives is recommended. A light, dull, non reflective surface works best for the scanning procedure.
- Model bases should be removable from the plaster that is used to attach the model to the articulator. The model bases should be flat, have minimal thickness and size, in order to ensure optical accessibility . A common split-cast system is recommended.
- Make sure that the base of the model is smooth and flat, without split-cast guides, metal plates or magnets. Defects and overlapping areas should be blocked out with light colored wax.
- All segments of the saw-cut model must be removable from the base with double, triple or block pin die system to prevent rotation or movement of the dies and pontic areas.
- Vertical walls and sharp line angles are difficult for scanning process to decipher. Avoid preparations with these situations (see Ideal Die Preparation).
- Margins should be ditched according to Ideal Die Preparation example below.

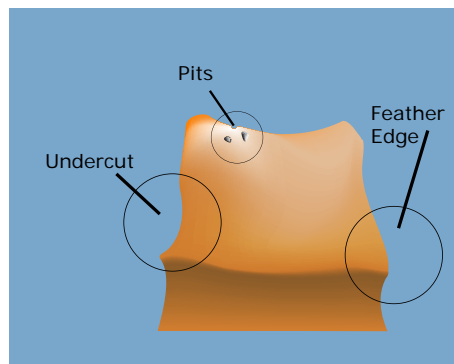
1. Ditch dies directly below the margin - **DO NOT** mark the margins. Also **DO NOT** use die spacer, or hardner on the die preparation area as this will create a reflective surface that will compromise the scanned data of the die surface. (Note proper angulations of the prep area)



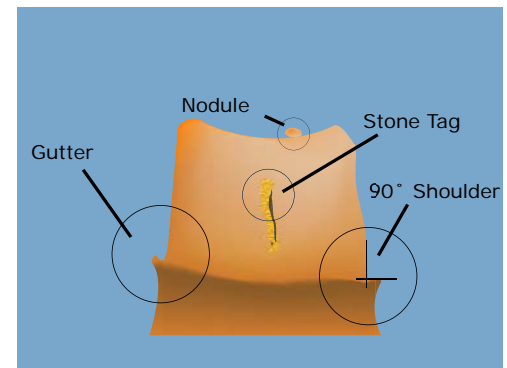
1. Ideal Die Preparation

2. Undercuts, occlusal holes, surface defects should be blocked with a resin block-out material, or a light colored wax.

Nodules, stone-tags should be scraped off.



2a. Contraindications



2b. Contraindications